

MITSUBISHI SEMICONDUCTOR <GaAs FET>
MGFS45A2527B

2.5 - 2.7GHz BAND 32W INTERNALLY MATCHED GaAs FET

DESCRIPTION

The MGFS45A2527B is an internally impedance-matched GaAs power FET especially designed for use in 2.5 - 2.7 GHz band amplifiers. The hermetically sealed metal-ceramic package guarantees high reliability.

FEATURES

- Class A operation
- Internally matched to 50(ohm) system
- High output power
P1dB = 32W (TYP.) @ f=2.5 - 2.7 GHz
- High power gain
GLP = 12 dB (TYP.) @ f=2.5 - 2.7GHz
- High power added efficiency
P.A.E. = 40 % (TYP.) @ f=2.5 - 2.7GHz
- 3rd order IM distortion
IM = -45dBc (TYP.) @ f=2.5 - 2.7GHz

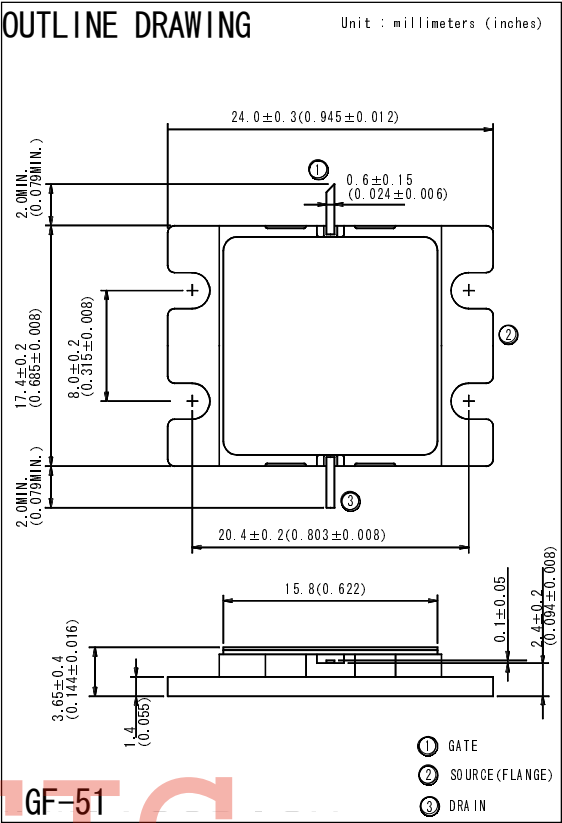
APPLICATION

- item 01 : 2.5 - 2.7 GHz band power amplifier
- item 51 : 2.5 - 2.7 GHz band digital ratio communication

QUALITY GRADE
GG

RECOMMENDED BIAS CONDITIONS

- VDS = 10 (V)
- ID = 6.5 (A)
- RG=25 (ohm)



ABSOLUTE MAXIMUM RATINGS (Ta=25deg.C)

Symbol	Parameter	Ratings	Unit
VGDO	Gate to drain voltage	-20	V
VGSO	Gate to source voltage	-10	V
PT *1	Total power dissipation	107	W
Tch	Channel temperature	175	deg.C
Tstg	Storage temperature	-65 / +175	deg.C

*1 : Tc=25deg.C

< Keep safety first in your circuit designs! >
Mitsubishi Electric Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (1) placement of substitutive, auxiliary circuits, (2) use of non-flammable material or (3) prevention against any malfunction or mishap.

ELECTRICAL CHARACTERISTICS (Ta=25deg.C)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
VGS(off)	Gate to source cut-off voltage	VDS = 3V , ID = 84mA	-	-	-5	V
P1dB	Output power	VDS=10V, ID(RF off)=6.5A, f=2.5 - 2.7GHz	44	45	-	dBm
GLP	Linear power gain		11	12	-	dB
ID	Drain current		-	7.5	-	A
P.A.E.	Power added efficiency		-	40	-	%
IM3 *2	3rd order IM distortion		-42	-45	-	dBc
Rth(ch-c) *3	Thermal resistance	delta Vf method	-	1.2	1.4	deg.C/W

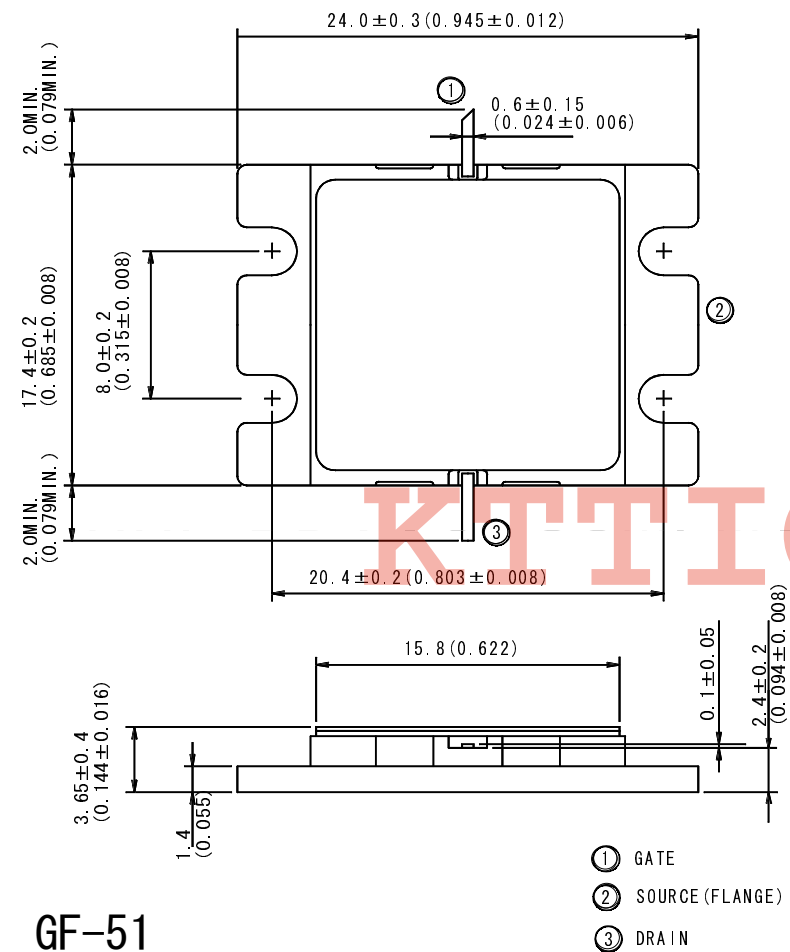
*2 : item -51, 2 tone test, Po=34.5dBm Single Carrier Level, f=2.5, 2.6, 2.7GHz, delta f=5MHz

*3 : Channel-case

S-band 30W Power GaAs FET

OUTLINE DRAWING

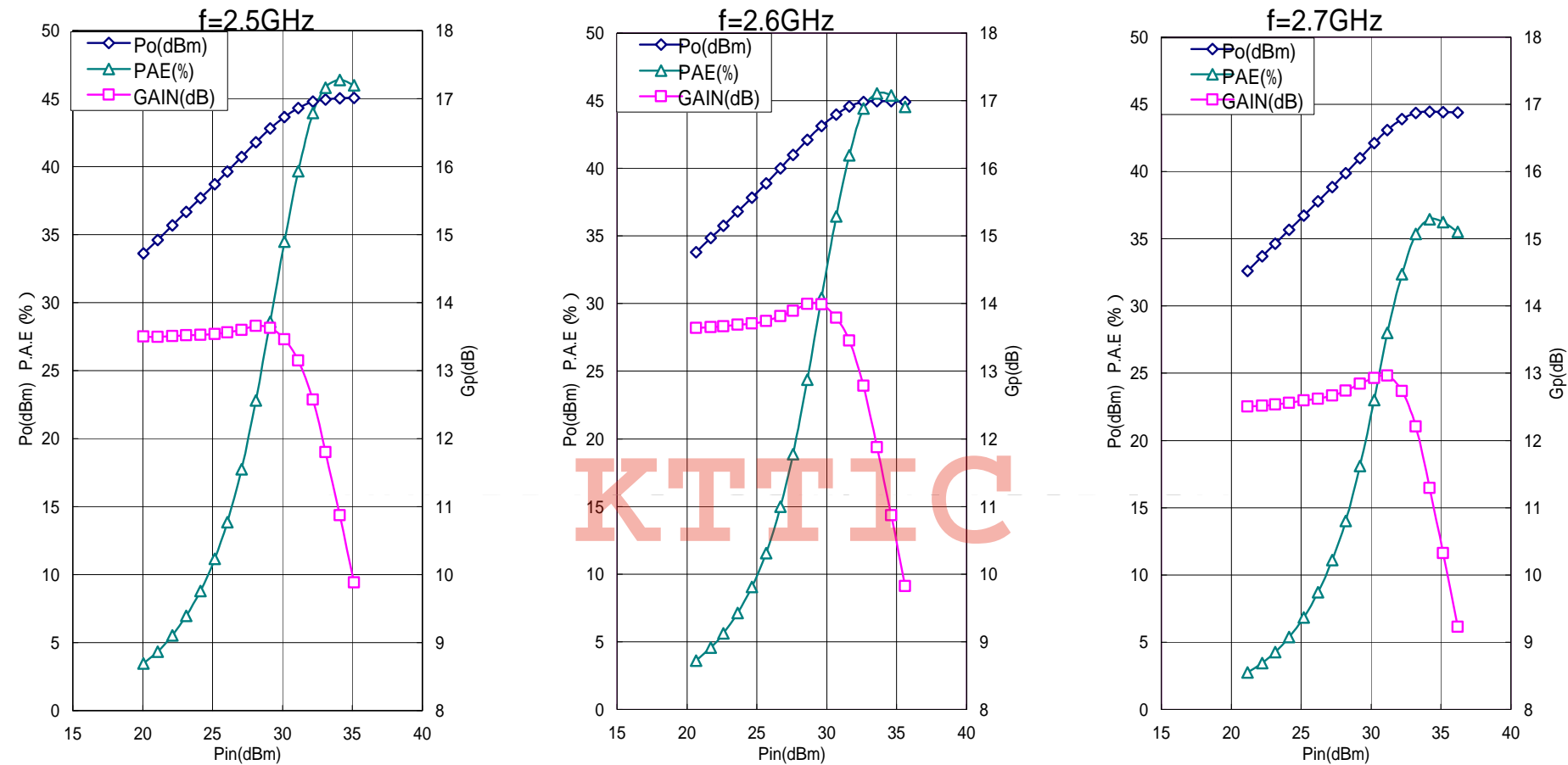
Unit : millimeters (inches)



GF-51

S-band 30W Power GaAs FET MGFS45A2527B

OUTPUT POWER & POWER ADDED EFFICIENCY vs. INPUT POWER



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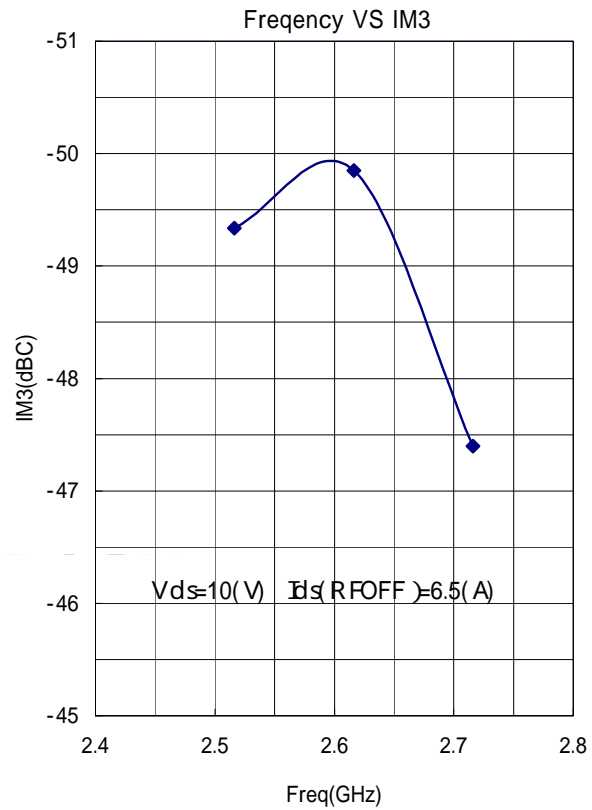
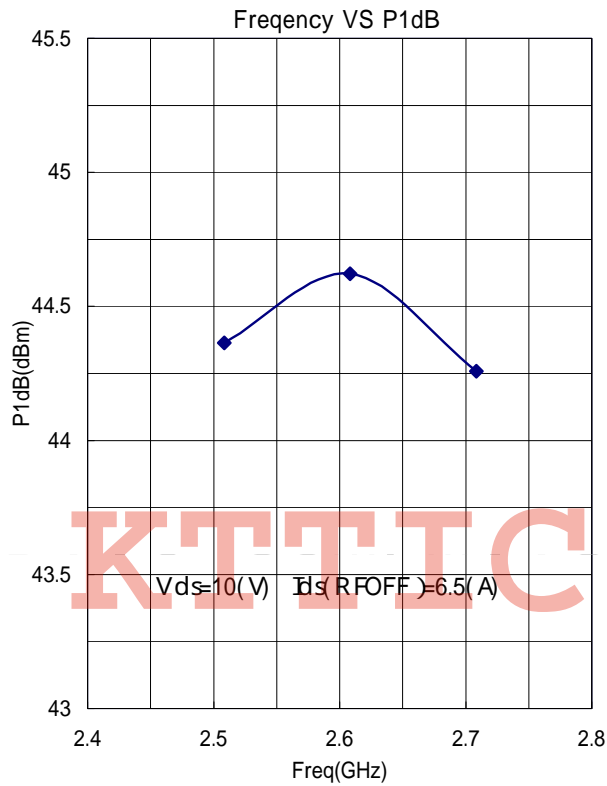
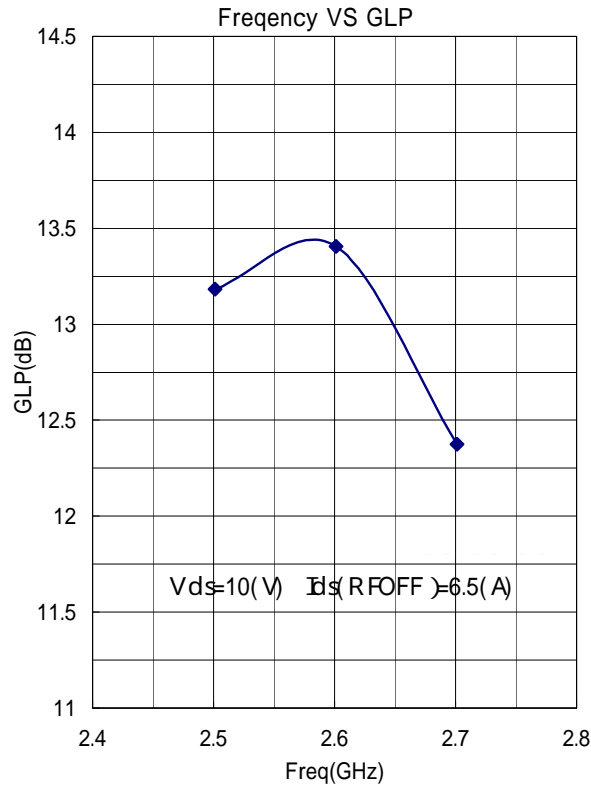
S PARAMETERES(T=25deg.C,VDS=10V,ID=6.5A)

Freq	S11		S21		S12		S22	
	(mag) (ang)		(mag) (ang)		(mag) (ang)		(mag) (ang)	
	(mag)	(ang)	(mag)	(ang)	(mag)	(ang)	(mag)	(ang)
2.00	0.88	74.01	1.42	-115.63	0.01	-79.30	0.79	101.57
2.05	0.87	67.63	1.56	-124.88	0.01	-86.26	0.77	95.64
2.10	0.85	60.94	1.72	-134.47	0.01	-102.29	0.75	89.25
2.15	0.82	53.50	1.91	-144.48	0.01	-111.11	0.73	83.20
2.20	0.79	45.38	2.12	-155.53	0.01	-129.00	0.70	75.83
2.25	0.76	36.25	2.38	-167.27	0.01	-140.42	0.67	67.92
2.30	0.72	26.06	2.66	-179.79	0.01	-159.19	0.64	58.86
2.35	0.66	14.95	2.99	166.21	0.02	176.25	0.59	47.67
2.40	0.59	1.86	3.34	150.86	0.02	155.14	0.54	34.08
2.45	0.51	-13.16	3.70	133.43	0.02	126.07	0.48	16.39
2.50	0.40	-31.23	4.01	115.11	0.02	98.68	0.43	-5.01
2.55	0.28	-51.53	4.24	95.76	0.02	71.43	0.39	-31.79
2.60	0.16	-78.16	4.32	75.62	0.02	43.53	0.38	-61.12
2.65	0.07	-146.41	4.27	55.31	0.02	15.41	0.40	-87.87
2.70	0.12	127.83	4.09	35.45	0.03	-11.45	0.45	-109.18
2.75	0.22	95.47	3.80	16.42	0.03	-33.34	0.49	-125.33
2.80	0.30	74.56	3.51	-1.65	0.03	-54.63	0.53	-137.70
2.85	0.38	56.47	3.18	-19.06	0.03	-75.33	0.57	-147.32
2.90	0.45	40.38	2.88	-35.49	0.03	-94.35	0.60	-154.95
2.95	0.51	24.35	2.58	-51.73	0.03	-111.68	0.62	-161.21
3.00	0.58	8.80	2.30	-67.16	0.03	-126.90	0.64	-166.56

This S-Parameter data show measurements performed on each single-ended FET

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Frequency characteristic



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